

AMENDMENTS TO THE CLAIMS

Please amend the present application as follows:

Claims

1-8. (Canceled)

9. (Withdrawn -- Currently amended) The method of claim 22 ~~4~~, additionally comprising attaching a semiconductor die to the die mounting pad.

10. (Withdrawn) The method of claim 9, additionally comprising:
providing a packaging device, the packaging device including a conductive mounting surface; and
mounting the device in the packaging device, the mounting comprising attaching the connecting pad to the conductive mounting surface of the packaging device.

11. (Withdrawn) The method of claim 9, in which:
providing a substrate comprises providing a wafer of which the substrate constitutes part; and
the method additionally comprises, after the filling, the forming and the attaching, singulating the wafer into individual devices.

12-15. (Canceled)

16. (Withdrawn -- Currently amended) The method of claim 11 ~~45~~, additionally comprising performing electrical testing prior to the singulating.

17. (Withdrawn -- Currently amended) The method of claim 11 ~~45~~, additionally comprising performing electro-optical testing prior to the singulating.

18. (Withdrawn -- Currently amended) The method of claim 9 ~~44~~, additionally comprising encapsulating the semiconductor die and at least a portion of the major ~~surface~~ surfaces of the substrate on which the die mounting pad is located.

19-21 (Canceled)

22. (Currently amended) A method for fabricating a device, the method comprising:
providing a substantially planar substrate having opposed major surfaces, the substrate comprising a through hole extending between the major surfaces;
providing a slug of an electrically conductive material interconnecting element;
squeezing the slug into the through hole whereby the slug is retained in the through hole by friction ~~introducing the electrically conductive interconnecting element into the through hole~~; and
forming an electrically conductive die mounting pad and an electrically conductive connecting pad on different ones of the major surfaces each pad being in electrical contact with the slug. ~~electrically conductive interconnecting element~~.

23. (Canceled)

24. (Currently amended) The method of claim 22 ~~23~~, wherein the slug has a diameter that is smaller than a diameter of the through hole, the smaller diameter selected to provide a friction fit between the slug and the through hole.

25. (Previously presented) The method of claim 24, wherein the ends of the slug are located approximately flush with the opposed major surfaces.

26. (Currently amended) The method of claim 22 ~~23~~, wherein the slug comprises tungsten.

27. (Currently amended) The method of claim 22, wherein the slug electrically conductive interconnecting element occupies at least a portion of a volume of the through hole.

28. (Currently amended) The method of claim 27, wherein an adhesive is used to hold the slug ~~electrically conductive interconnecting element~~ in the through hole.